

Title (en)
Micro-heater and sensor

Title (de)
Mikro-Heizelement und Fühler

Title (fr)
Micro-chauffage et capteur

Publication
EP 1688714 B1 20091104 (EN)

Application
EP 06002511 A 20060207

Priority
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Abstract (en)
[origin: EP1688714A2] A micro-heater including a semiconductor substrate (100) having a cavity (130,150); an insulating layer (200) provided on an upper side of the semiconductor substrate and closing the cavity; and a heater element (400) embedded in a portion of the insulating layer above the cavity and including a metallic material. The insulating layer includes: a compressive stress film made of silicon oxide; and a tensile stress film made of silicon nitride. The tensile stress film has a thickness not less than that of the compressive stress film.

IPC 8 full level
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CPC (source: EP KR US)
G01F 1/68 (2013.01 - KR); **G01F 1/6845** (2013.01 - EP US); **G01P 5/12** (2013.01 - KR); **H01L 29/84** (2013.01 - KR);
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DE FR

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US 2006174703 A1 20060810; US 7487675 B2 20090210

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